# 2SA1171

## Silicon PNP Epitaxial

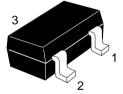
# **HITACHI**

### Application

Low frequency small signal amplifier

#### Outline

MPAK



- 1. Emitter
- 2. Base
- 3. Collector



### 2SA1171

### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{\text{CBO}}$	<b>-</b> 90	V
Collector to emitter voltage	V <sub>CEO</sub>	-90	V
Emitter to base voltage	$V_{EBO}$	<b>-</b> 5	V
Collector current	I <sub>c</sub>	-50	mA
Collector power dissipation	P <sub>c</sub>	150	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

#### **Electrical Characteristics** (Ta = 25°C)

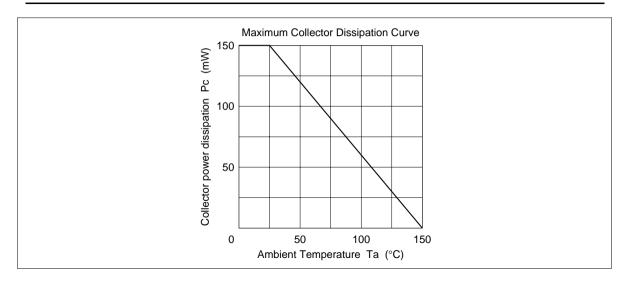
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-90	_	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Collector cutoff current	I <sub>CBO</sub>	_	_	-0.5	μΑ	$V_{CB} = -75 \text{ V}, I_{E} = 0$
DC current transfer ratio	h <sub>FE</sub> *1	250	_	800		$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Base to emitter voltage	V <sub>BE</sub>		_	-0.75	V	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-0.5	V	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$
Gain bandwidth product	f <sub>T</sub>	_	200	_	MHz	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Collector output capacitance	Cob	_	1.6	_	pF	$V_{CB} = -25 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

Note: 1. The 2SA1171 is grouped by  $h_{\rm FE}$  as follows.

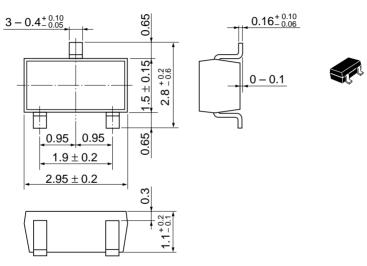
Grade	D	E
Mark	PD	PE
h <sub>FE</sub>	250 to 500	400 to 800

See characteristic curves of 2SA872.

## 2SA1171



Unit: mm



Hitachi Code	MPAK
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.011 g

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